

TECHNICAL DATA SHEET 2/4						
STR	AIGHT FEMALE	Н	R110.422.100			
	-		Series : MMCX			
PACKAGINGStandardUnitOther100'W' optionContact us			SPECIFICATION			
ELECTRICAL CHARACTERISTICS			ENVIRONMENTAL			
Frequency0VSWRAD + 0.0Insertion lossARF leakage- (		Ω GHz x F(GHz) Maxi √F(GHz) dB Maxi - F(GHz)) dB Maxi Veff Maxi	Operating temper Hermetic seal Panel leakage	rature -55/+155 ° C NA Atm.cm3/s NA		
Dielectric withstanding voltage500Veff miniInsulation resistance1000MΩ mini			OTHERS CHARACTERISTICS			
			Assembly instruc	ction		
			Others :			
MECHAN	ICAL CHARACTE	RISTICS	-			
Center contact retent Axial force – Matin Axial force – Oppos Torque Recommended torqu	g end 10 site end 10 NA	N mini N mini N.cm mini				
Mating Panel nut	NA	N.cm N.cm				
Mating life Weight	500 0.390	Cycles mini g				
<b>Issue : 0422 A</b> In the effort to improve necessary.	e our products, we reserve	the right to make cha	anges judged to be			

## TECHNICAL DATA SHEET

## STRAIGHT FEMALE, END LAUNCH

**R110.422.100** Series : **MMCX** 

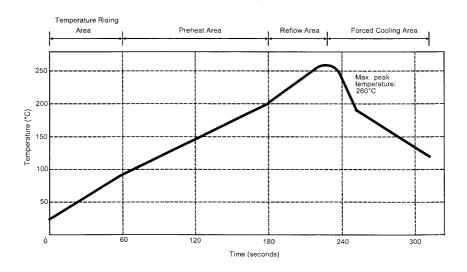
## **SOLDER PROCEDURE**

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 microns (0.006 inch). Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

## **TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec



3/4

